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Should be replaced with:

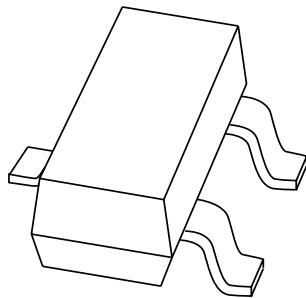
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via salesaddresses@nexperia.com). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DATA SHEET



PMBD353

Schottky barrier double diode

Product data sheet
Supersedes data of 1999 May 25

2001 Oct 15

Schottky barrier double diode

PMBD353

FEATURES

- Low forward voltage
- Small SMD package
- Low capacitance.

APPLICATIONS

- UHF mixer
- Sampling circuits
- Modulators
- Phase detection.

DESCRIPTION

Planar Schottky barrier double diode in a SOT23 small plastic SMD package.

MARKING

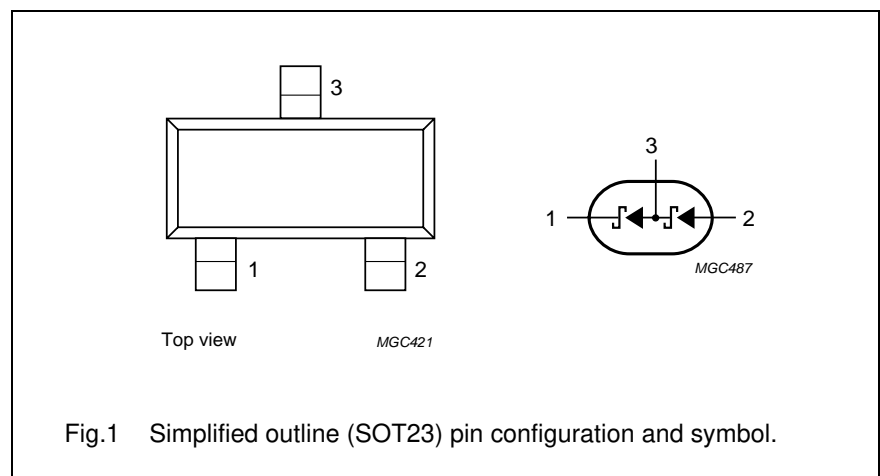
TYPE NUMBER	MARKING CODE ⁽¹⁾
PMBD353	*4F

Note

- * = p: Made in Hong Kong.
 * = t: Made in Malaysia.
 * = W: Made in China.

PINNING

PIN	DESCRIPTION
1	cathode k ₁
2	anode a ₂
3	common connection a ₁ , k ₂



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
Per diode				
V _R	continuous reverse voltage	–	4	V
I _F	continuous forward current	–	30	mA
T _{stg}	storage temperature	–65	+150	°C
T _j	junction temperature	–	100	°C

Schottky barrier double diode

PMBD353

ELECTRICAL CHARACTERISTICS $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
Per diode				
V_F	forward voltage	see Fig.2 $I_F = 0.1\text{ mA}$ $I_F = 1\text{ mA}$ $I_F = 10\text{ mA}$	350 450 600	mV mV mV
I_R	reverse current	$V_R = 3\text{ V}$; note 1; see Fig.3	0.25	μA
C_d	diode capacitance	$f = 1\text{ MHz}$; $V_R = 0$; see Fig.4	1	pF

Note

1. Pulse test: $t_p = 300\text{ }\mu\text{s}$; $\delta = 0.02$.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

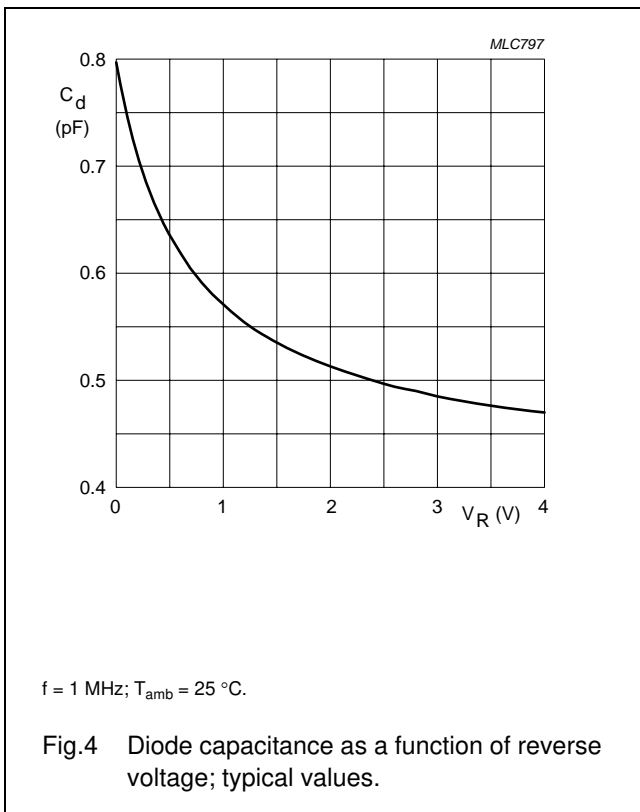
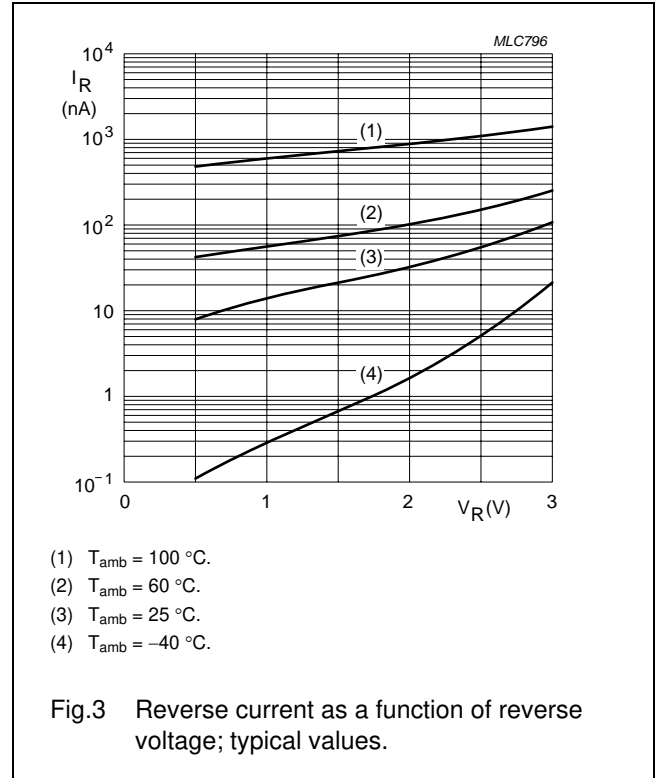
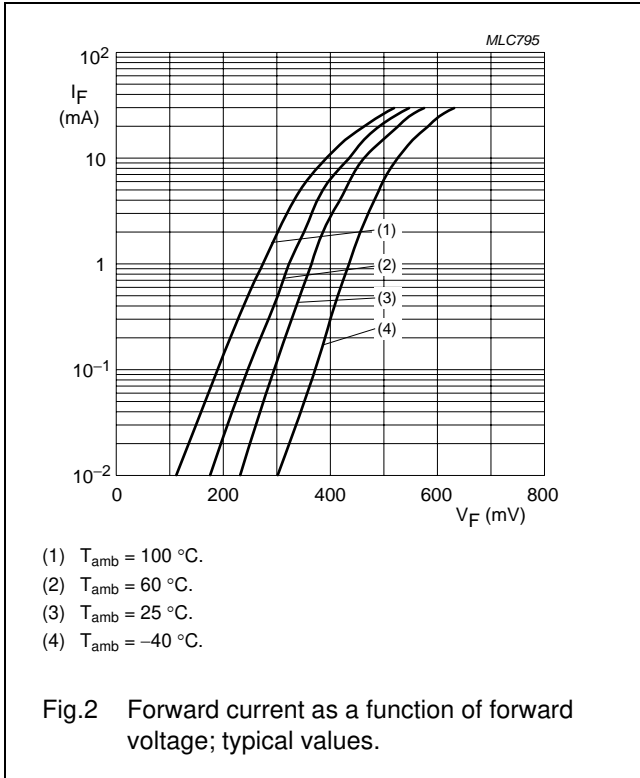
Note

1. Refer to SOT23 standard mounting conditions.

Schottky barrier double diode

PMBD353

GRAPHICAL DATA



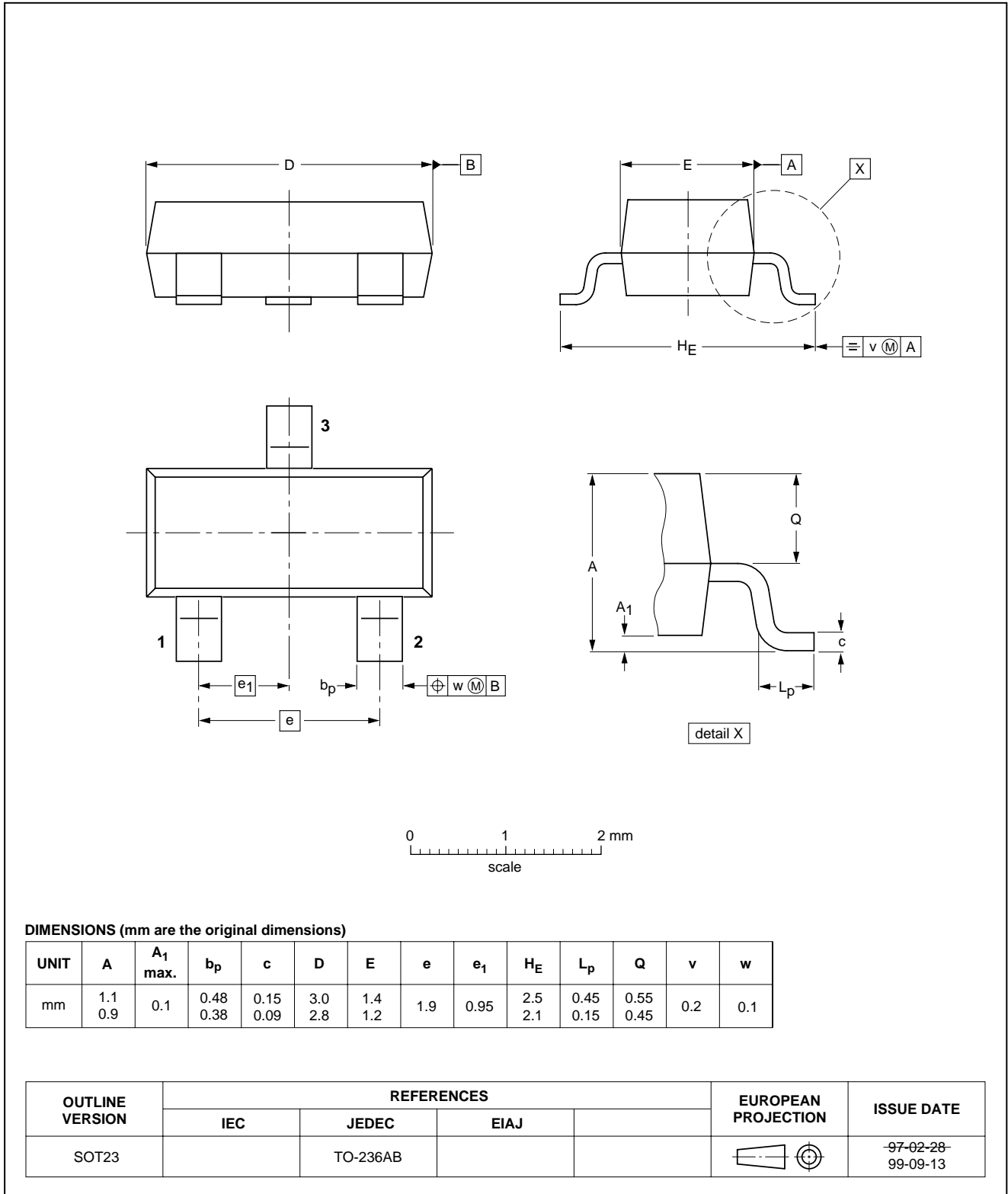
Schottky barrier double diode

PMBD353

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



Schottky barrier double diode

PMBD353

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

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Contact information

For additional information please visit: **<http://www.nxp.com>**

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